CMOS IC

LC86E6032



8-Bit Single-Chip Microcontroller

Preliminary

Overview

The LC86E6032 microcontroller is a CMOS 8-bit single chip microcontroller with UVEPROM for LC866000A series.

This microcontroller has the same functions and pin assignment as for the LC866000A series mask ROM version, and a 32K-byte EPROM.

Program data is rewritable. It is suitable for program developments.

Features

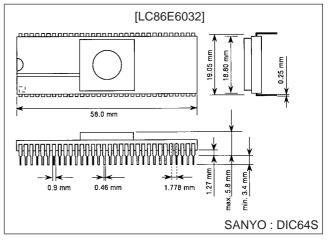
- Option switching using EPROM data The optional functions of the LC866000A series can be specified using EPROM data. LC86E6032 can be checked the functions of trial piece using the mass production board.
- (2) Internal 32K-byte UVEPROM 32K-byte UVEPROM (ultraviolet erasable and programmable ROM) is built in. This corresponds to LC866032B/28B/24B/20A/16A/12A/08A.
- (3) The pin compatible with mask ROM version
- (4) Factory shipment DIC-64S QFC-64E

(Under development)

Package Dimensions

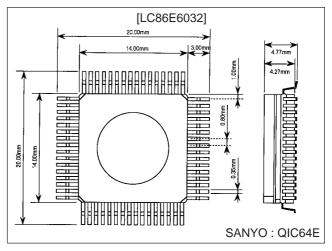
unit : mm

3126-DIC64S



unit : mm

3152-QFC64E



- Any and all SANYO products described or contained herein do not have specifications that can handle applications that require extremely high levels of reliability, such as life-support systems, aircraft's control systems, or other applications whose failure can be reasonably expected to result in serious physical and/or material damage. Consult with your SANYO representative nearest you before using any SANYO products described or contained herein in such applications.
- SANYO assumes no responsibility for equipment failures that result from using products at values that exceed, even momentarily, rated values (such as maximum ratings, operating condition ranges, or other parameters) listed in products specifications of any and all SANYO products described or contained herein.

SANYO Electric Co., Ltd. Semiconductor Bussiness Headquarters TOKYO OFFICE Tokyo Bldg., 1-10, 1 Chome, Ueno, Taito-ku, TOKYO, 110-8534 JAPAN

Notice for Use

LC86E6032 is provided for the program development and checking the function of LC866000A series. At using, take notice of the followings.

(1) Reset

It is necessary to be sure to go into 'L' level and hold for 200 μ s to reset terminal ($\overline{\text{RES}}$) after power supplied voltage has been over inferior limit of supply voltage.

The option is specified until 3ms after going into 'H' level to reset terminal by degrees.

The program is executed from 00H of program counter. The output form of all ports are N-channel open-drain while 'L' level to reset terminal.

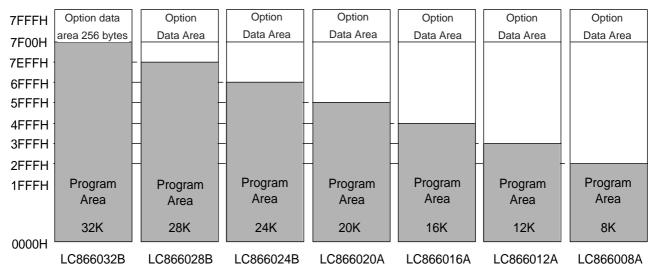
(2) Option

The LC86E6032 uses 256 bytes addressed 7F00H to 7FFFH in program memory as option data area.

This area does not affect the execution of program but means that the LC866032A program memory is 32512 bytes addressed 0000H to 7EFFH.

The option data is specified by the option-setting program "SU866000.EXE". The specified option data is linked to the program area by linkage editor "L866000.EXE".

(3) ROM space



(4) Points of difference LC86E6032 and LC866000A series (mask ROM version)

Item	LC86E6032	LC866032B/28B/24B/20A/16A/12A/08A
Operating temperature range	+10°C to +40°C	-30°C to +70°C
(Topr)		
Output form of port at reset	Open-drain output	Output form specified by option data
Output form of segment	Pulldown resistance	Pulldown resistance: Provided/ Not provided
S0/T0 to S6/T6	Not provided	Specified by option
S7/T7 to S15/T15	Provided (fixed)	Provided (fixed)
S16 to S23	Provided (fixed)	Specified by option
S24 to S29	Not provided	Specified by option
Operating supply	4.5 to 6.0V	2.5 to 6.0V
voltage range (VDD)		

Option

A kind of option corresponding LC86E6032

Option types	Pins, Circuits	Contents of option
Input/output form of input/output ports	Port 0 (specified in a bit)	1. Input No Pullup MOS Transistor Output :N-channel open-drain :Pullup MOS Transistor Output :CMOS
	Port 1 (specified in a bit)	 Input :Programmable pullup MOS Transistor Output :N-channel open-drain Input :Programmable pullup MOS Transistor Output :CMOS
Pullup MOS Transistor	Port 7	1. No Pullup MOS Transistor
of input port	(specified in a bit)	2. Pullup MOS Transistor

A kind of option not corresponding LC86E6032

Option types	Pins,Circuits	Contents of option
Pulldown resistance of high voltage withstand output terminal	S0/T0 to S6/T6 S16 to S29 (specified in a bit)	 Pulldown resistance No Pulldown resistance

How to Use

(1) Specification of options

LC86E6032 must be programmed after specifying option data. The option is specified by "SU866000.EXE". The specified option file and the file created by our macro assembler "M866000.EXE" are linked by our linkage loader "L866000.EXE" which creates .HEX file, then the option code is put in the option specifed area (7F00H to 7FFFH) of its .HEX file.

(2) How to write data to EPROM

When writing data that was created by the linker to the LC86E6032, a general-purpose EPROM programmer can be used by using special write conversion boards (W86EP6032D, W86EP6032Q).

Supplier	EPROM programmer
Advantest	R4945, R4944, R4943
Andou	AF-9704
AVAL	PKW-1100, PKW-3000
Minato Electronics	MODEL 1890A

• Recommended EPROM programmers

- "27512 (Vp-p = 12.5 V) Intel high-speed programming" mode should be used. The address must be set to "0000H to 7FFFH" and the jumper (DASEC) must be set 'OFF' at programming.
- (3) How to use the data security function

"Data security" is a function to prevent the EPROM data from being read. Instructions on using the data security function:

- 1. Set the jumper (DASEC) of the attachment 'ON'.
 - 2. Attempt to program the EPROM.
 - The EPROM programmer displays an error. The error is a result of normal activity of the data security feature, and does not indicate a problem with the programmer or the LSI.

Notes

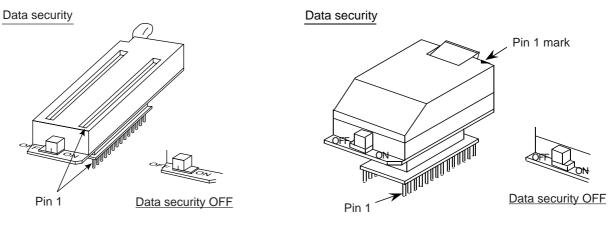
- The data security function is not carried out when the data of all address contain 'FF' at step 2 above.
- · Data security cannot be executed when the sequential writing operation of programming
- "BLANK=>PROGRAM=>VERIFY" is used at step 2 above.
- Set the jumper 'OFF' after the execution of data security.

(4) Erasing data

Use a general-purpose EPROM eraser to erase the written data.

(5) Shielding

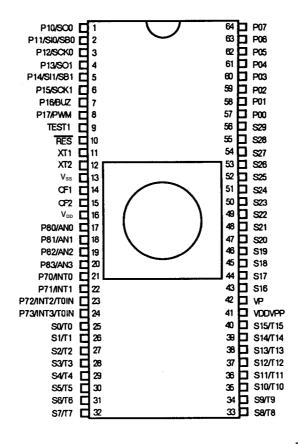
The UVEPROM (ultraviolet erasable programmable ROM) is incorporated in the IC. Cover the window of the IC with a seal in use.



W86EP6032D

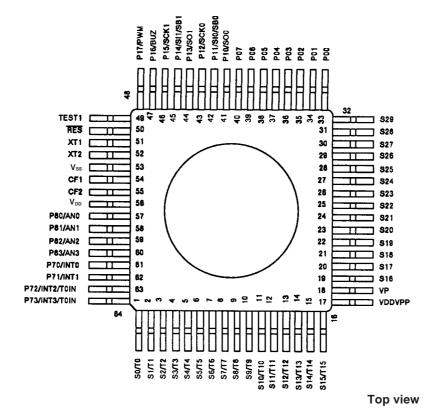
W86EP6032Q

Pin Assignment

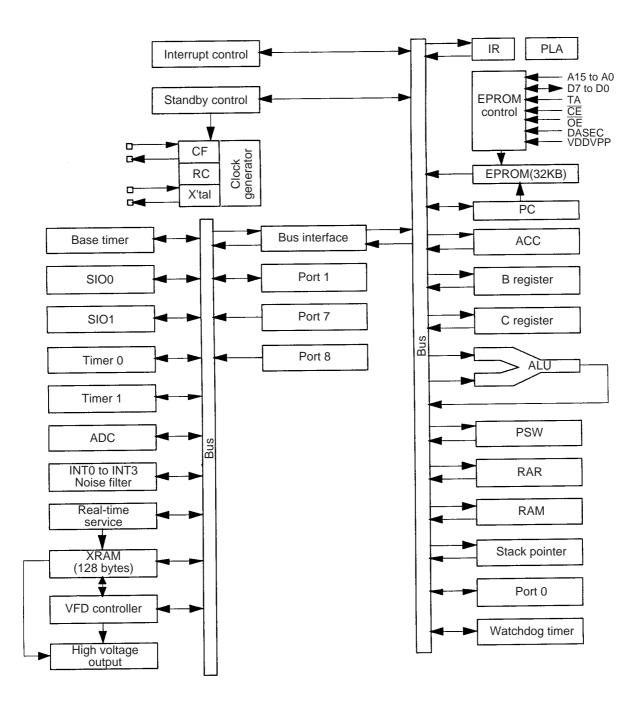


Top view

Pin Assignment



System Block Diagram



Pin Description

Pin name	I/O		Functi	ion descrip	tion			Opt	ion	Function in PROM mode
V _{SS}	—									
V _{DD}	_	Power supply pin (+)								
VP		(Powe	supply pin r supply fo r supply fo	r VFD disp	lay drive ou resistor)	itput)				
VDDVPP	_	Power	supply pin	(+)						Power for programming
PORT0 P00 to P07	I/O	 Input for 4 Input 	input/outpu t/output spe -bit unit. t for HOLD t for port 0	release	can be mad	e	P • O	ull-up resis rovided/No putput form I-channel c	t provided : CMOS/	
PORT1 P10 to P17	1/0	 8-bit input/output port Data direction can be specified for each bit. Other pin functions P10 : SIO0 data output P11 : SIO0 data input/ bus input/output P12 : SIO0 clock input/output P13 : SIO1 data output P14 : SIO1 data input/ bus input/output P15 : SIO1 clock input/output P16 : Buzzer output P17 : Timer 1 output (PWM output) 				Data input/output • D0 to D7				
PORT7 P70 P71 to P73	I/O I	• Othe P70 P71 P72 P73	transisto : INT 1 inp : INT 2 inp : INT 3 inp event in	ons ut/HOLD re r output for ut/HOLD re ut/timer 0 e ut with nois put.	lease/N-cha watchdog elease. event input. se filter/time vector addr	timer. er 0		ull-up resis rovided/No		Input of PROM control signal • DASEC (*1) • \overrightarrow{OE} (*2) • \overrightarrow{CE} (*3)
			Rising	Falling	Rising & falling		gh /el	Low level	Vector	
		INT0	Enable	Enable	Disable	Ena	able	Enable	03H	
		INT1	Enable	Enable	Disable	Ena	able	Enable	0BH	
		INT2	Enable	Enable	Enable	Disa	able	Disable	13H	
		INT3	Enable	Enable	Enable	Disa	Disable Disable 1BH		1BH	
PORT8 P80 to P83	I	Othe	input port r functions nput port (4		1				, I	
S0/T0 to S6/T6	0	Output for VFD display controller Segment/timing common output								
S7/T7 to S15/T15	0	Seg	t for VFD d ment/timing out with bui	g common						•S14/T14 : TA (*4) •S15/T15 : A14 (*5)

Continued on next page.

Continued from preceding page.

Pin name	I/O	Function description	Option	Function in PROM mode
S16 to S23	0	Output for VFD display controller Segment output Output with built-in pull-down resistor		Address input •A13 to A0
S24 to S29	0	Output for VFD display controller Segment output		
RES	I	Reset pin		
TEST1	0	Test pin Should be left open.		
XT1	I	Input pin for 32.768 kHz crystal oscillation When not used, connect to V_{DD} .		
XT2	0	Output pin for 32.768 kHz crystal oscillation When not used, should be left open.		
CF1	I	Input pin for ceramic resonator oscillation		
CF2	0	Output pin for ceramic resonator oscillation		

*1 Memory select input for data security

*2 Output enable input

*3 Chip enable input

*4 TA \rightarrow PROM control signal input

*5 A14 \rightarrow Address input

* All of port options can be specified in bit unit.

* A state of pins at reset.

Pin name	Input/output mode	A state of pullup resistor specified at pullup option
Ports 0,7	Input	Fixd pullup resistor exsists
Port 1	Input	Programmable pullup resistor OFF

Pin name	A state of P-channel transistor
S0/T0 to S15/T15	P-channel transistor OFF
S16 to S29	P-channel transistor OFF

Specification

1. Absolute Maximum Ratings at $Ta=25^\circ C,\,V_{SS}=0$ V

Para	meter	Symbol	Pins	Conditions		Ratings			
					V _{DD} [V]	min	typ	max	
Maximu voltage	m supply	V _{DD} max	V _{DD} ,VDDVPP	V _{DD} = VDDVPP		-0.3		+7.0	V
Input vo	ltage	V _I (1)	• P 71, 72, 73 • <u>Port</u> 8 • RES			-0.3		V _{DD} +0.3	
		VI(2)	VP			V _{DD} -45		V _{DD} +0.3	
Output v	voltage	Vo	• S0/T0 to S15/T15 • S16 to S29			V _{DD} –45		V _{DD} +0.3	
Input/ou voltage	itput	Vio	Ports 0, 1,P 70			-0.3		V _{DD} +0.3	
High- level	Peak output	I _{OPH} (1)	Ports 0, 1	CMOS output At each pin		-4			mA
output current	current	I _{OPH} (2)	S0/T0 to S15/T15	At each pin		-30			
ourront		IOPH(3)	S16 to S29	At each pin		-15			
	Total	∑Іоан(1)	Port 0	Total of all pins		-10			
	output current	∑Іоан(2)	Port 1	Total of all pins		-10			
	ounon	∑I _{ОАН} (3)	• S0/T0 to S15/T15 • S16 to S29	Total of all pins		-130			
Low- level	Peak output	I _{OPL} (1)	Ports 0, 1	At each pin				20	
output current	current	I _{OPL} (2)	P70	At each pin				15	
	Total output	$\Sigma I_{OAL}(1)$	Port 0	Total of all pins				-30	
	current	$\Sigma I_{OAL}(2)$	Port 1,P70	Total of all pins				40	
	le power	Pd max(1)	DIC64S	$Ta = +10^{\circ}C$ to $+40^{\circ}C$				760	mW
dissipation		Pd max(2)	QFC64E	$Ta = +10^{\circ}C$ to $+40^{\circ}C$		To be dete	ermined aft	er evaluation	
Operatir tempera	ng iture range	Topr				+10		+40	°C
Storage tempera	ture range	Tstg				-65		150	

2. Allowable Operating Conditions at Ta $\,$ = +10 $^{\circ}C$ to $\,$ +40 $^{\circ}C, \,\, V_{SS} \,$ = 0 V

Parameter					Ratings		Unit	
				Vdd[V]	min	typ	max	
Operating supply voltage range	V _{DD}	V _{DD}	0.98 μs ≤ tCYC tCYC ≤ 400 μs		4.5		6.0	V
HOLD voltage	V _{HD}	V _{DD}	 When in HOLD mode RAM and registers retain previous data. 		2.0		6.0	
Pulldown supply voltage	VP	VP		4.5 to 6.0	-35		Vdd	
Input high-level voltage	V _{IH} (1)	Port 0 (Schmitt)	Output disable	4.5 to 6.0	0.4V _{DD} +0.9		V _{DD}	
	V _{IH} (2)	• Port 1 • P72, 73 (Schmitt)	Output disable	4.5 to 6.0	0.75V _{DD}		V _{DD}	
	Vih(3)	P70 Port input/interrupt. <u>P71</u> RES (Schmitt)	Output N-channel transistor OFF	4.5 to 6.0	0.75V _{DD}		V _{DD}	
	V _{IH} (4)	P70 Watchdog timer	Output N-channel transistor OFF	4.5 to 6.0	0.9V _{DD}		Vdd	
	V _{IH} (5)	Port 8		4.5 to 6.0	0.75V _{DD}		V _{DD}	
Input low-level	V _{IL} (1)	Port 0 (Schmitt)	Output disable	4.5 to 6.0	V _{SS}		0.2V _{DD}	
voltage	V _{IL} (2)	Port 1P72, 73(Schmitt)	Output disable	4.5 to 6.0	Vss		0.25V _{DD}	
	V _{IL} (3)	•P70 Port input/interrupt. •P71 •RES (Schmitt)	N-channel transistor OFF	4.5 to 6.0	V _{SS}		0.25V _{DD}	
	VIL(4)	P70 Watchdog timer	N-channel transistor OFF	4.5 to 6.0	Vss		0.8V _{DD} -1.0	
	VIL(5)	• Port 8		4.5 to 6.0	Vss		0.25V _{DD}	
Operation cycle time	tCYC			4.5 to 6.0	0.98		400	μs
Oscillation frequency range (Note 1)	FmCF(1)	CF1, CF2	 12 MHz (ceramic resonator oscillation). Refer to Figure 1. 	4.5 to 6.0	11.76	12	12.24	MHz
	FmCF(2)	CF1, CF2	 3 MHz (ceramic resonator oscillation). Refer to Figure 1. 	4.5 to 6.0	2.94	3	3.06	
	FmRC		RC oscillation	4.5 to 6.0	0.4	0.8	2.0	
	FsXtal	XT1, XT2	 32.768 kHz (crystal oscillation). Refer to Figure 2. 	4.5 to 6.0		32.768		kHz
Oscillation stable time period (Note 1)	tmsCF(1)	CF1, CF2	 12 MHz (ceramic resonator oscillation). Refer to Figure 3. 	4.5 to 6.0		0.02	0.2	ms
	tmsCF(2)	CF1, CF2	 3 MHz (ceramic resonator oscillation). Refer to Figure 3. 	4.5 to 6.0		0.1	1	
	tssXtal	XT1, XT2	 32.768 kHz (crystal oscillation). Refer to Figure 3. 	4.5 to 6.0		1	1.5	S

(Note 1) Refer to Table 1 and Table 2 for the oscillation constants.

3. Electrical Characteristics at Ta= +10 $^{\circ}C$ to +40 $^{\circ}C$, $\,V_{SS}$ = 0 V

Parameter	Symbol	Pins	Conditions	Ra	atings		Unit	
				V _{DD} [V]	min	typ	max	
Input high-level current	lı _H (1)	Port 1 Port 0 without pull-up MOS transistor	Output disable Pull-up MOS transistor OFF. VIN = VDD (including off-state leak current of output transistor)	VDD [V] min typ max tput disable lup MOS transistor F. 4.5 to 6.0 1 1 = VDD uding off-state leak ant of output sistor) 4.5 to 6.0 1 1 = VDD 4.5 to 6.0 -1 1 = VDD 4.5 to 6.0 -1 1 = VSS 4.5 to 6.0 -1 1 = VSS 4.5 to 6.0 -1 1 = VSS 4.5 to 6.0 -1 1 = -1.0 mA 4.5 to 6.0 VDD-1 1 = -1.0 mA 4.5 to 6.0 VDD-1.8 1 = -1.0 mA 4.5 to 6.0 VDD-1 1 = -1.0 mA 4.5 to 6.0 VDD-1	μA			
	I _{IH} (2)	Port 7 without pull-up MOS transistor Port 8	V _{IN} = V _{DD}	4.5 to 6.0			1	
	I _{IH} (3)	• RES	$V_{IN} = V_{DD}$	4.5 to 6.0			1	
Input low-level current	lıL(1)	Port 1 Port 0 without pull-up MOS transistor	 Output disable Pull-up MOS transistor OFF. VIN = VSS (including off-state leak current of output transistor) 		-1			
	lı∟(2)	Port 7 without pull-up MOS transistor Port 8	V _{IN} = V _{SS}	4.5 to 6.0	-1			
	I _{IL} (3)	• RES	VIN = VSS	4.5 to 6.0	-1			
Output high-level voltage	V _{OH} (1)	• Ports 0, 1 at CMOS	I _{OH} = -1.0 mA	4.5 to 6.0	V _{DD} -1			V
	V _{OH} (2)	output	I _{OH} = -0.1 mA	4.5 to 6.0	V _{DD} -0.5			
	V _{OH} (3)	S0/T0 to S15/T15	I _{OH} = -20 mA	4.5 to 6.0	V _{DD} -1.8			
	V _{ОН} (4)		 I_{OH}= -1.0 mA The current of any unmeasurement pin is not over 1 mA. 	4.5 to 6.0	V _{DD} -1			
	V _{OH} (5)	S16 to S29	I _{OH} = -5 mA	4.5 to 6.0	V _{DD} -1.8			
-	V _{OH} (6)	_	• I _{OH} = -1.0 mA • The current of any unmeasurement pin is not over 1 mA.	4.5 to 6.0	V _{DD} -1			
Output low-level	V _{OL} (1)	Ports 0,1	I _{OL} = 10 mA	4.5 to 6.0			1.5	
Vutput low-level voltage	V _{OL} (2)		 I_{OL} = 1.6 mA The total current of the Ports 0,1 is not over 40 mA 				0.4	
ŀ	V _{OL} (3)	P70	IOL = 1 mA	4.5 to 6.0			0.4	
Pull-up MOS transistor resistor	Rpu	• Ports 0, 1 • Port 7	V _{OH} = 0.9 V _{DD}	4.5 to 6.0	15	40	70	kΩ
Output off-state leak current	IOFF(1)	• S0/T0 to S6/T6 • S24 to S29 (Without pulldown	•Output P-channel transistor OFF. •V _{OUT} = Vss	4.5 to 6.0	-1			μΑ
-	I _{OFF} (2)	resistor)	• Output P-channel transistor OFF. • V _{OUT} = V _{DD} -40V	4.5 to 6.0	-30			

Continued on next page.

Continued from preceding page.

Parameter Symbol Pins		Pins	Conditions			Unit		
				V _{DD} [V]	min	typ	max	
Pulldown resistor	R _{pd}	• S7/T7 to S15T15 • S16 to S23 (With pulldown resistor)	 Output P-channel transistor OFF. V_{OUT}= 3V VP= -30V 	5.0	60	100	200	kΩ
Hysteresis voltage	V _{HIS}	• Ports 0,1 • Port 7 • RES	Output disable	4.5 to 6.0		0.1V _{DD}		V
Pin capacitance	СР	All pins	 f=1MHz Unmeasurement terminals for input are set to V_{SS} level. Ta= 25°C 	4.5 to 6.0		10		pF

4. Serial Input/Output Characteristics at $Ta=+10^{\circ}C$ to $+40^{\circ}C$, $~V_{SS}=0~V$

F	Paran	neter	Symbol	Pins	Conditions			Unit		
						V _{DD} [V]	min	typ	max	
		Cycle	tCKCY(1)	SCK0, SCK1	Refer to Figure 5.	4.5 to 6.0	2			tCYC
	Input clock	Low- level pulse width	tCKL(1)	_		4.5 to 6.0	1			
Serial clock	dul	High- level pulse width	tCKH(1)			4.5 to 6.0	1			
		Cycle	tCKCY(2)	SCK0, SCK1	 Use pull-up resistor (1 kΩ) when set to open-drain output. 	4.5 to 6.0	2			
	Output clock	Low- level pulse width	tCKL(2)		• Refer to Figure 5.	4.5 to 6.0		1/2tCKCY		
		High- level pulse width	tCKH(2)			4.5 to 6.0		1/2tCKCY		
input	Data set-up		tICK	• SI0, SI1 • SB0, SB1	Data set-up to SCK0, 1	4.5 to 6.0	0.1			μs
Serial input	Data time	a hold 9	tCKI		• Refer to Figure 5.	4.5 to 6.0	0.1			
Serial output	Output delay time (Serial clock is extrnal clock.)		tCKO(1)	• SO0, SO1 • SB0, SB1	 Data hold from SCK0, 1 Use pull-up resistor (1 kΩ) when set to open-drain output. Refer to Figure 5. 	4.5 to 6.0			7/12tCYC +0.2	
Seria	time (Ser	rial clock ternal	tCKO(2)	• SO0, SO1 • SB0, SB1	 Data hold from SCK0, 1 Use pull-up resistor (1 kΩ) when set to open-drain output. Refer to Figure 5. 	4.5 to 6.0			1/3tCYC +0.2	

5. Pulse Input Conditions at Ta = $+10^{\circ}$ C to $+40^{\circ}$ C, V_{SS} = 0 V

Parameter	Symbol	Pins	Conditions	Conditions		Ratings		Unit	
				V _{DD} [V]	min	typ	max		
High/low-level pulse width	tPIH(1) tPIL(1)	• INT0, INT1 • INT2/T0IN	 Interrupt acceptable Timer 0 pulse countable 	4.5 to 6.0	1			tCYC	
	tPIH(2) tPIL(2)	INT3/T0IN (The noise rejection clock selected to 1/1.)	 Interrupt acceptable Timer 0 pulse countable 	4.5 to 6.0	2				
	tPIH(3) tPIL(3)	INT3/T0IN (The noise rejection clock selected to 1/64.)	 Interrupt acceptable Timer 0 pulse countable 	4.5 to 6.0	128				
	tPIL(4)	RES	Reset acceptable	4.5 to 6.0	200			μs	

6. A/D Converter Characteristics at Ta = $+10^{\circ}$ C to $+40^{\circ}$ C, V_{SS} = 0 V

Parameter	Symbol	Pins	Conditions		Ratings		gs	Unit
				V _{DD} [V]	min	typ	max	
Resolution	Ν			4.5 to 6.0		8		bit
Absolute precision	ET		(Note 2)				±1.5	LSB
Conversion time	tCAD		A/D conversion time = 16 x tCYC (ADCR2 = 0) (Note 3) A/D conversion time = 32 x tCYC (ADCR2 = 1) (Note 3)	-	15.68 (tCYC = 0.98 μs) 31.36 (tCYC = 0.98 μs)		65.28 (tCYC = 4.08 μs) 130.56 (tCYC = 4.08 μs)	μs
Analog input voltage range	Vain	AN0 to AN3			Vss		Vdd	V
Analog port	I _{AINH}	1	VAIN = VDD				1	μA
input current	I _{AINL}	1	V _{AIN} = V _{SS}		-1			

(Note 2) Absolute precision excepts quantizing error ($\pm 1/2$ LSB).

(Note 3) The conversion time is the time from execution of the instruction to start conversion to the completion of shifting the A/D converted value to the register.

7. Current Drain Characteristics at $Ta=+10^\circ C$ to $+40^\circ C$, $~V_{SS}=0~V$

Parameter	Symbol Pins		Conditions	Conditions		Ratings		
				V _{DD} [V]	min	typ	max	
Current drain during basic operation (Note 4)	IDDOP(1)	VDD	 FmCF = 12 MHz for ceramic resonator oscillation. FsXtal = 32.768 kHz for crystal oscillator. System clock : 12 MHz side Internal RC oscillator stopped. 	4.5 to 6.0		13	26	mA
	Iddop(2)	IDDOP(2)	 FmCF = 3 MHz for ceramic resonator oscillation. FsXtal = 32.768 kHz for crystal oscillator. System clock : 3 MHz side Internal RC oscillator stopped. 	4.5 to 6.0		6.5	14	
	IDDOP(3)		 FmCF = 0 Hz (when oscillator stops). FsXtal = 32.768 kHz for crystal oscillator. System clock : RC oscillator. 	4.5 to 6.0		4	10	
	Iddop(4)		 FmCF = 0 Hz (when oscillator stops). FsXtal = 32.768 kHz for crystal oscillator. System clock : 32.768 kHz side Internal RC oscillator stopped. 	4.5 to 6.0		3.5	9	

Continued on next page.

Continued from preceding page.

Parameter	Symbol	Pins	Conditions		Ratings			Unit	
				V _{DD} [V] min		min typ max]	
Current drain at HALT mode (Note 4)	Iddhalt(1)	VDD	 HALT mode FmCF = 12 MHz for ceramic resonator oscillation. FsXtal = 32.768 kHz for crystal oscillator. System clock : 12 MHz side Internal RC oscillator stopped. 	4.5 to 6.0		5	10	mA	
	IDDHALT(3) • FmCF IDDHALT(3) • HALT r • FsXtal crystal • System 3 MHz • Interna stopped • HALT r • FmCF (when d) • FsXtal crystal • System RC osc • System IDDHALT(4) • HALT r • FmCF = (when d) • System • System • Interna • System 32.768 • Interna		 HALT mode FmCF = 3 MHz for ceramic resonator oscillation. FsXtal = 32.768 kHz for crystal oscillator. System clock : 3 MHz side Internal RC oscillator stopped. 	4.5 to 6.0		1.8	4.6		
			 HALT mode FmCF = 0 Hz (when oscillator stops). FsXtal = 32.768 kHz for crystal oscillator. System clock : RC oscillator 	4.5 to 6.0		400	800	μΑ	
		 HALT mode FmCF = 0 Hz (when oscillator stops). FsXtal = 32.768 kHz for crystal oscillator. System clock : 32.768 kHz side Internal RC oscillator stopped. 	4.5 to 6.0		20	60			
Current drain at HOLD mode	IDDHOLD(1)	Vdd	HOLD mode	4.5 to 6.0		0.05	30		
(Note 4)	IDDHOLD(2)]		2.5 to 4.5		0.02	20		

(Note 4) The currents of output transistors and pull-up MOS transistors are ignored.

Oscillation type	Supplier	Oscillator	C1	C2
12 MHz ceramic resonator	Murata	CSA12.0MTZ	33 pF	33 pF
oscillation		CSA12.0MT	33 pF	33 pF
		CST12.0MTW	on c	hip
	Kyocera	KBR-12.0M	33 pF	33 pF
3 MHz ceramic resonator	Murata	CSA3.00MG	33pF	33 pF
oscillation	cillation		on c	hip
	Kyocera	KBR-3.0MS	47 pF	47 pF

* Both C1 and C2 must use K rank ($\pm 10\%$) and SL characteristics.

Table 1. Ceramic Resonator Oscillation Guaranteed Constants (Main-clock)

Oscillation type	Supplier	Oscillator	C3	C4
32.768 kHz crystal oscillation	Dai Sinku	DT-38(1TA252E00)	18 pF	18 pF
	Kyocera	KF-38G-13P0200	18 pF	18 pF

* Both C3 and C4 must use J rank ($\pm 5\%$) and CH characteristics.

(If high precision is unnecessary, use K rank (±10%) and SL characteristics.)

Table 2. Crystal Oscillation Guaranteed Constants (Sub-clock)

Notes • Since the circuit pattern affects the oscillation frequency, place the oscillation-related parts as close to the oscillation pins as possible with the shortest pattern length.

• If you use other oscillators herein, we provide no guarantee for the characteristics.

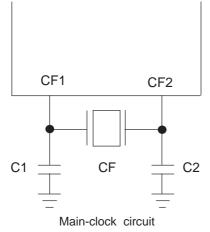
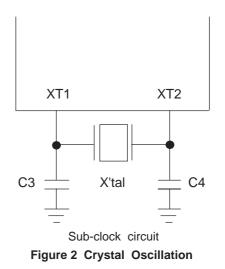
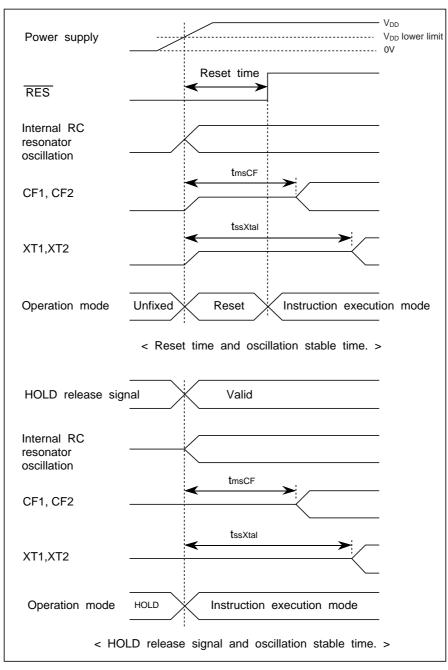


Figure 1 Ceramic Resonator Oscillation







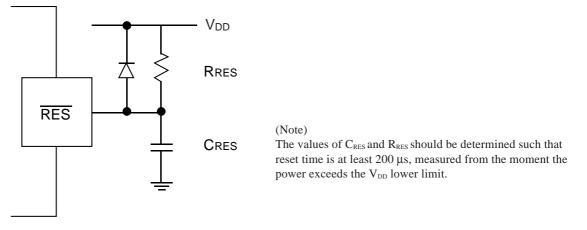


Figure 4 Reset Circuit



< AC timing point >

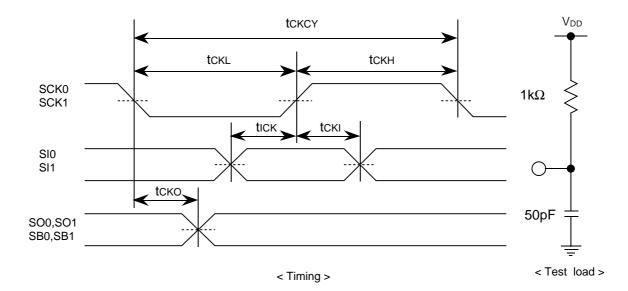


Figure 5 Serial Input/Output Test Conditions

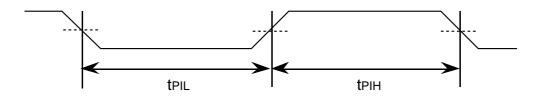


Figure 6 Pulse Input Timing Conditions

Specifications of any and all SANYO products described or contained herein stipulate the performance, characteristics, and functions of the described products in the independent state, and are not guarantees of the performance, characteristics, and functions of the described products as mounted in the customer's products or equipment. To verify symptoms and states that cannot be evaluated in an independent device, the customer should always evaluate and test devices mounted in the customer's products or equipment.

SANYO Electric Co., Ltd. strives to supply high-quality high-reliability products. However, any and all semiconductor products fail with some probability. It is possible that these probabilistic failures could give rise to accidents or events that could endanger human lives, that could give rise to smoke or fire, or that could cause damage to other property. When designing equipment, adopt safety measures so that these kinds of accidents or events cannot occur. Such measures include but are not limited to protective circuits and error prevention circuits for safe design, redundant design, and structural design.

- In the event that any or all SANYO products(including technical data, services) described or contained herein are controlled under any of applicable local export control laws and regulations, such products must not be exported without obtaining the export license from the authorities concerned in accordance with the above law.
- No part of this publication may be reproduced or transmitted in any form or by any means, electronic or mechanical, including photocopying and recording, or any information storage or retrieval system, or otherwise, without the prior written permission of SANYO Electric Co., Ltd.
- Any and all information described or contained herein are subject to change without notice due to product/technology improvement, etc. When designing equipment, refer to the "Delivery Specification" for the SANYO product that you intend to use.
- Information (including circuit diagrams and circuit parameters) herein is for example only ; it is not guaranteed for volume production. SANYO believes information herein is accurate and reliable, but no guarantees are made or implied regarding its use or any infringements of intellectual property rights or other rights of third parties.

This catalog provides information as of December, 1998. Specifications and information herein are subject to change without notice.